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**AMENDMENTS TO THE SPECIFICATION**

[0004] A rectangular array of openings 50 is defined in each hard tray 5, the openings receiving corresponding BGA sockets 7 therein. Two pairs of extending portions 54 are formed in each opening 50, for supporting a corresponding BGA socket 7. A bottom portion 52 is defined in the opening 50 so as to prevent the hard tray 5 from generating thermal and stress warpage. Moreover, the bottom portion 52 protects soldering balls of the BGA socket 7 from being damaged or contaminated. A relatively smooth surface 520 is formed on a bottom of the bottom portion 52.